

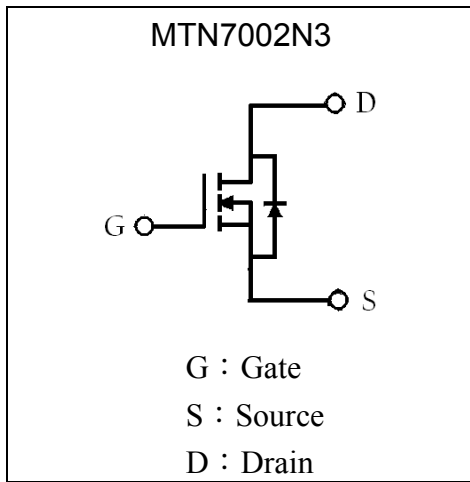
N-CHANNEL MOSFET

MTN7002N3

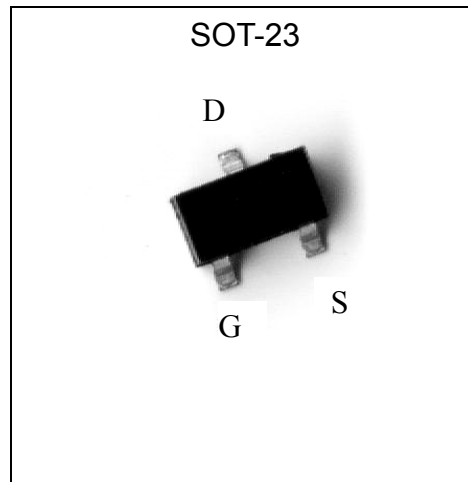
Description

The MTN7002N3 is a N-channel enhancement-mode MOSFET.

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	BV_{DSS}	60	V
Drain-Gate Voltage ($R_{GS}=1M\Omega$)	BV_{DGR}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_a=25^\circ C$)	I_D	200 *1	mA
Continuous Drain Current ($T_a=100^\circ C$)	I_D	115 *1	mA
Pulsed Drain Current ($T_a=25^\circ C$)	I_{DM}	800 *2	mA
Total Power Dissipation ($T_a=25^\circ C$)	P_D	200	mW
Total Power Dissipation ($T_c=25^\circ C$)		500	
Operating Junction Temperature	T_j	-55~+150	$^\circ C$
Storage Temperature	T_{stg}	-55~+150	$^\circ C$
Thermal Resistance, Junction-to-Ambient	$R_{th,ja}$	625	$^\circ C/W$
Thermal Resistance, Junction-to-Case	$R_{th,jc}$	250	$^\circ C/W$
Lead Temperature, for 10 second Soldering	T_L	240	$^\circ C$

Note : *1. The power dissipation of the package may result in a continuous drain current

*2. Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$



Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{DSS}	60	-	-	V	V _{GS} =0, I _D =10μA
V _{GS(th)}	1	-	2.5	V	V _{DS} =2.5V, I _D =0.25mA
I _{GSS/F}	-	-	100	nA	V _{GS} =+20V, V _{DS} =0
I _{GSS/R}	-	-	-100	nA	V _{GS} =-20V, V _{DS} =0
I _{DSS}	-	-	1	μA	V _{DS} =60V, V _{GS} =0
I _{D(ON)}	500	-	-	mA	V _{DS} >2V _{DS(ON)} , V _{GS} =10V
V _{DS(ON)}	-	-	0.375	V	I _D =50mA, V _{GS} =5V
	-	-	3.75	V	I _D =500mA, V _{GS} =10V
R _{DS(ON)}	-	-	7.5	Ω	I _D =50mA, V _{GS} =5V
	-	-	7.5		I _D =500mA, V _{GS} =10V
G _{FS}	80	-	-	mS	V _{DS} >2V _{DS(ON)} , I _D =200mA
C _{iss}	-	-	50	pF	V _{DS} =25V, V _{GS} =0, f=1MHz
C _{oss}	-	-	25		
C _{rss}	-	-	5		

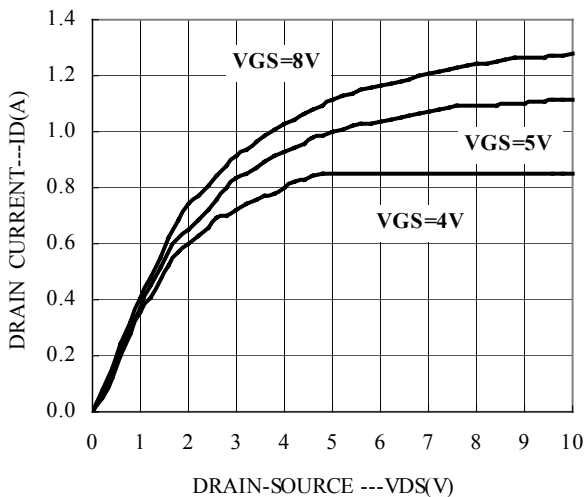
*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

Ordering Information

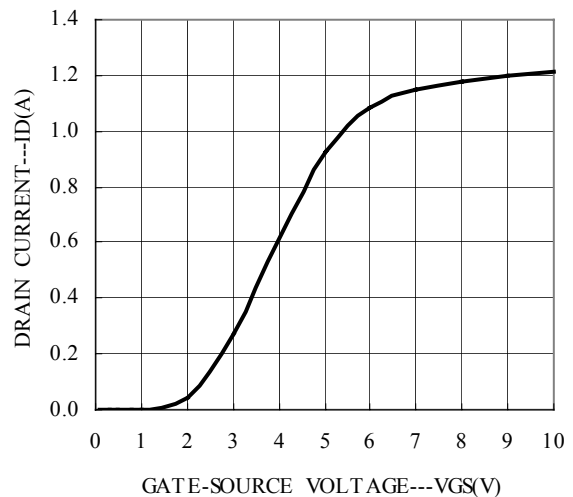
Device	Package	Shipping	Marking
MTN7002N3	SOT-23	3000 pcs / Tape & Reel	702

Characteristic Curves

TYPICAL OUTPUT CHARACTERISTICS



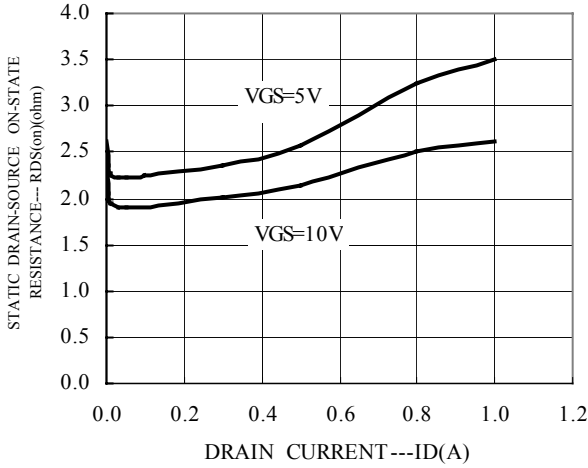
TYPICAL TRANSFER CHARACTERISTIC



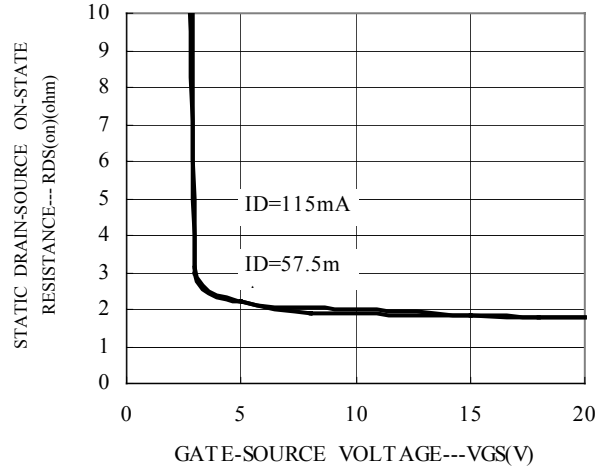


Characteristic Curves(Cont.)

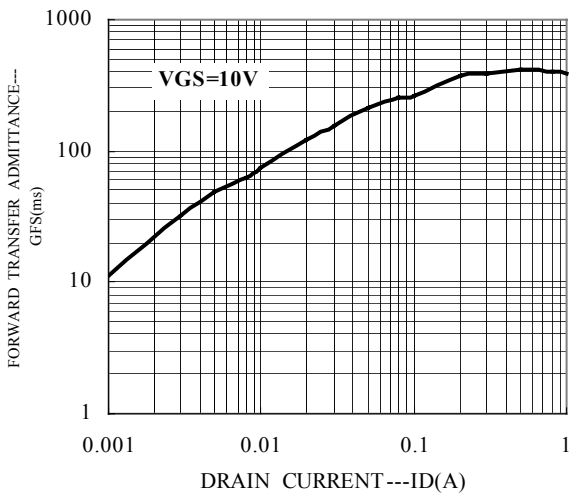
STATIC DRAIN-SOURCE ON-STATE RESISTANCE vs DRAIN CURRENT



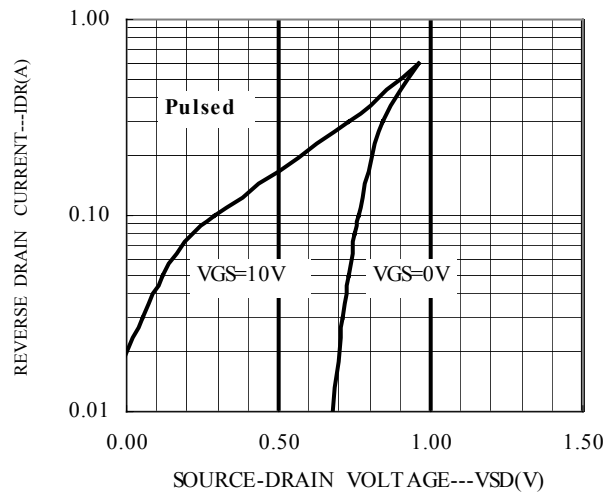
STATIC DRAIN-SOURCE ON-STATE RESISTANCE VS GATE-SOURCE VOLTAGE



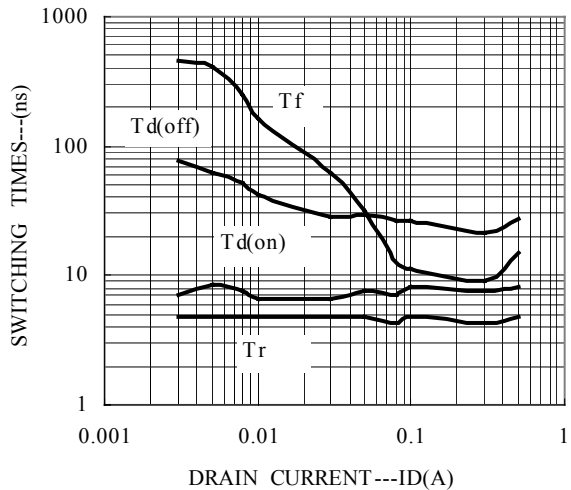
FORWARD TRANSFER ADMITTANCE vs DRAIN CURRENT



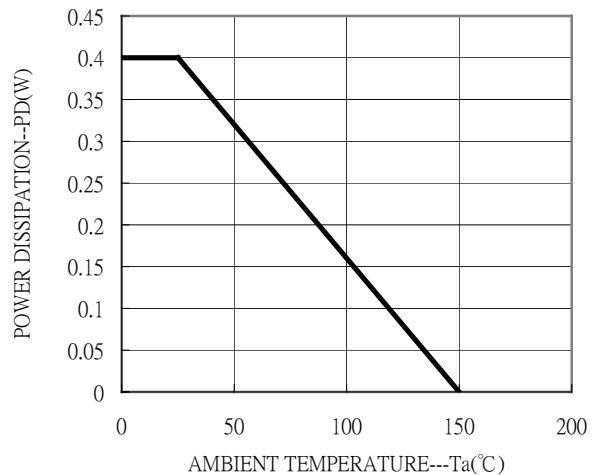
REVERSE DRAIN CURRENT vs SOURCE-DRAIN VOLTAGE



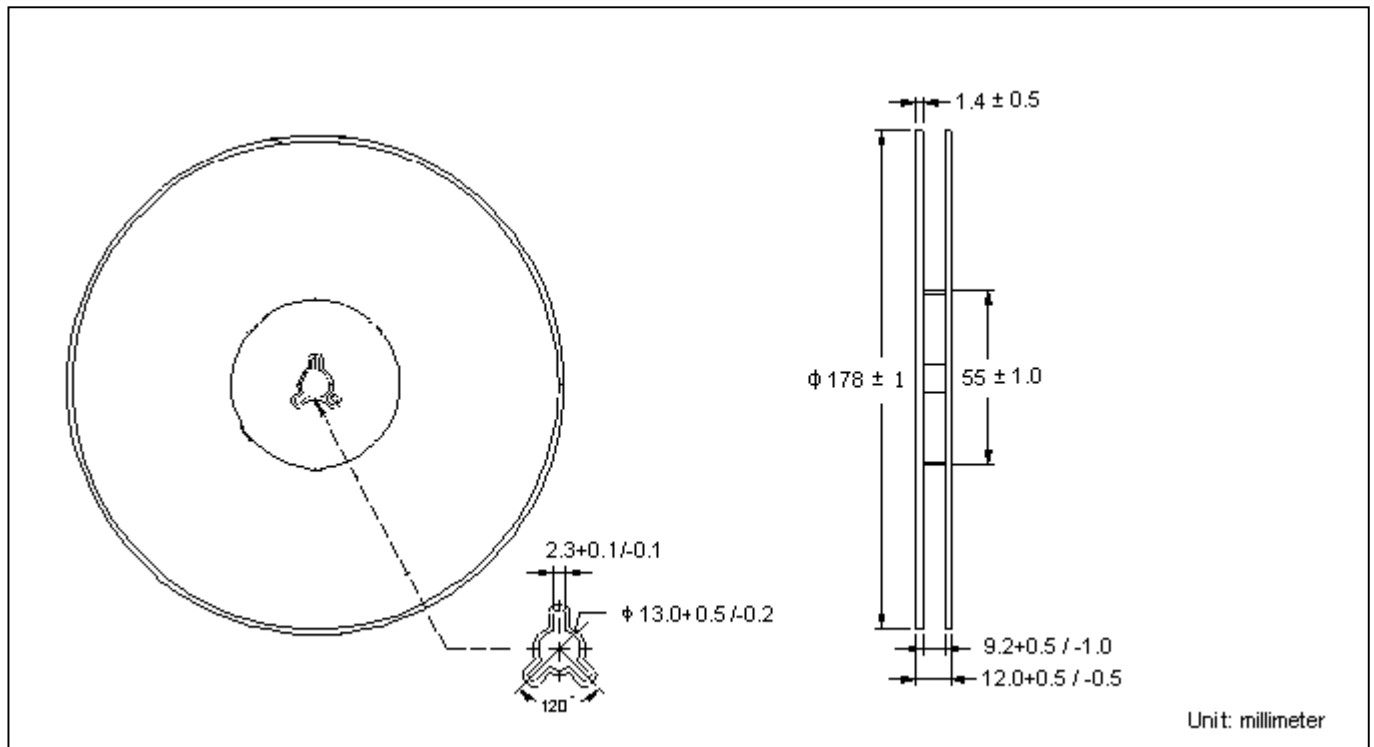
SWITCHING CHARACTERISTICS



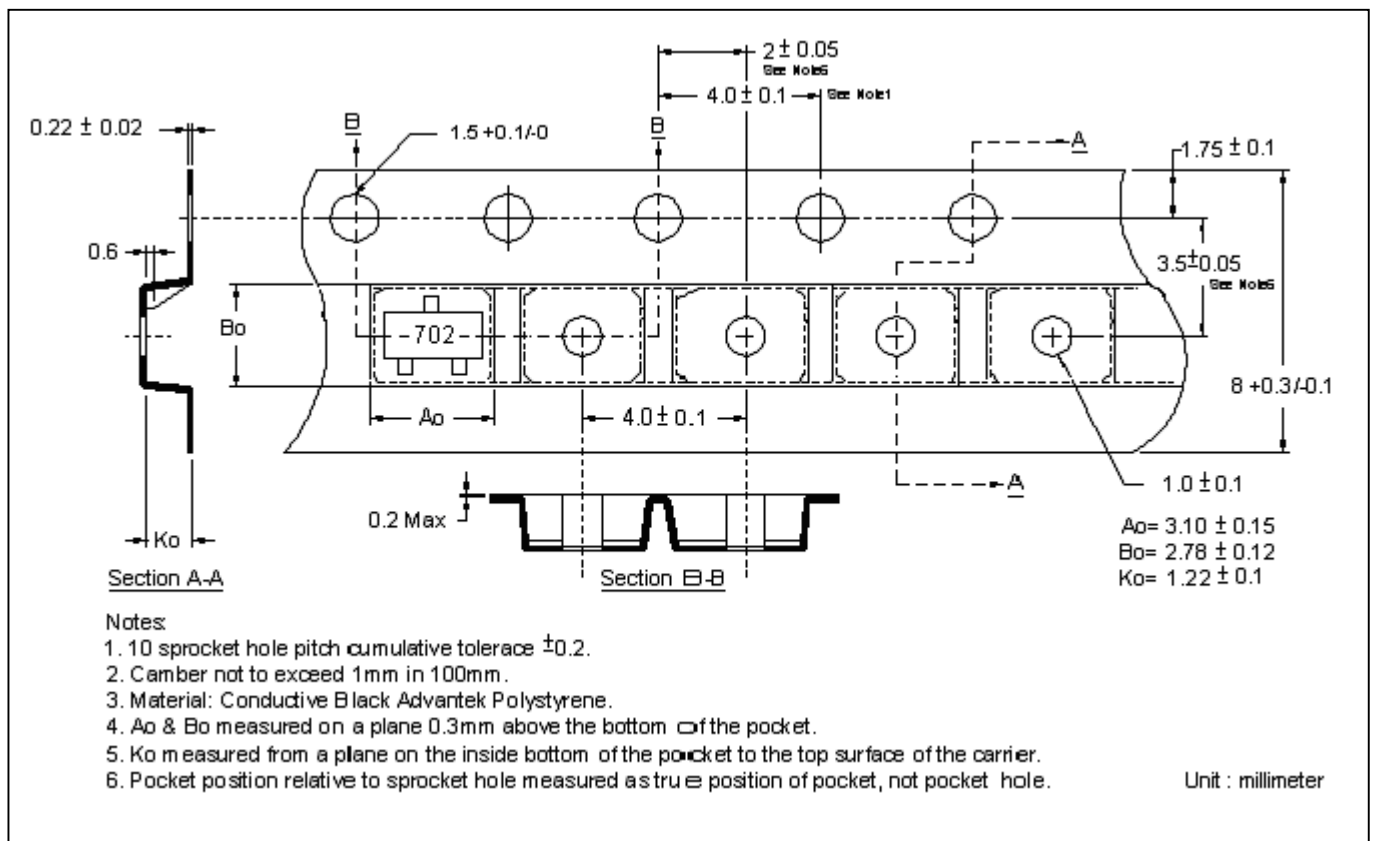
POWER DERATING CURVE



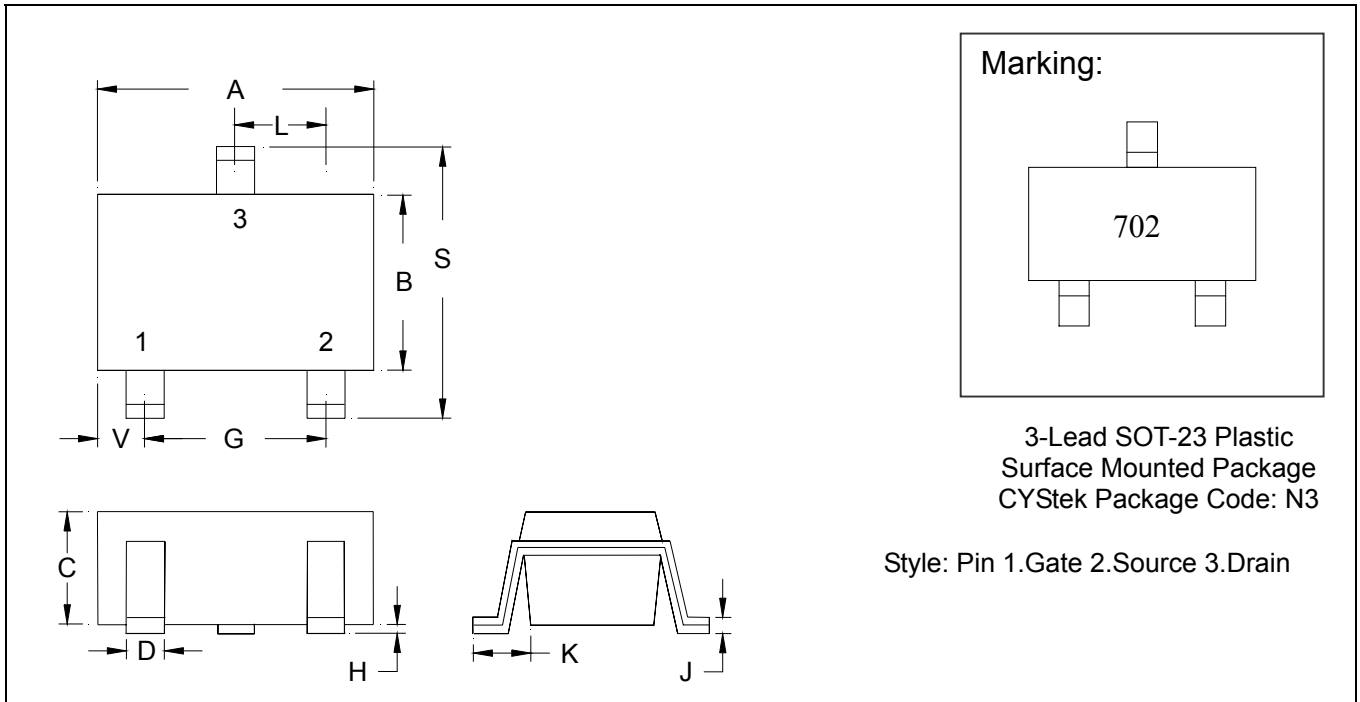
Reel Dimension



Carrier Tape Dimension



SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

- Notes:** 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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